	2/15/2013		PMP8903 REVB BOM			
Qty	Ref Des	Value	Description	Size	Part Number	MFR
7	C6 C16-18 C20 C22 C25	0.1uF	Capacitor, Ceramic, 50V, X7R, 15%	603	STD	TDK
1	C5	1000pF	Capacitor, Ceramic, 50V, NPO, 15%	603	STD	TDK
1	C100	1500pF	Capacitor, Ceramic, 50V, NPO, 15%	603	STD	TDK
1	C23	15pF	Capacitor, Ceramic, 50V, NPO, 15%	603	STD	TDK
2	C4 C14	1uF	Capacitor, Ceramic, 16V, X7R, 15%	603	STD	TDK
1	C27	68pF	Capacitor, Ceramic, 50V, NPO, 15%	603	STD	TDK
1	C13	DNP	Capacitor, Ceramic, 50V, X7R, 15%	603	STD	TDK
4	C19 C21 C24 C26	10uF	Capacitor, Ceramic, X7R, 10V, ±10%	805	C2012X7R1A106M125AC	TDK
3	C1-3	10uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	C3225X7R1H106M250AC	TDK
4	C7-10	47uF	Capacitor, Ceramic, 10V, ±20%	1210	C3225X5R1A476M250AC	TDK
2	C11-12	open	Capacitor, Ceramic, 10V, ±20%	1210	C3225X5R1A476M250AC	TDK
1	C15	22uF	Capacitor, Alum, 50V, ±20%	6.3x5.8mm	EEEFK1H220P	Panasonic
6	D2-7	B1100	Diode, Schottky, 1A, 100V	SMA	B1100	Diodes Inc.
1	D1	SBR8U60P5	Diode, Schottky, 8A, 60V	Power DI5	SBR8U60P5	Diodes Inc
1	L4	22uH	Inductor, Coupled, 7.8A, ±10%	15 x 15 mm	JA4590AL	Coilcraft
2	L1-2	1uH	Inductor, SMT, 2.5A, 42 milliohm	4x4mm	LPS4018-102ML	Coilcraft
1	U1	LM3481MM	IC, Low-Side N-Ch Controller	MSOP	LM3481MM	TI
1	R1	0	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R10	10	Resistor, Chip, 1/16W, 1%	603	STD	STD
3	R6 R13 R16	100K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R8	10K	Resistor, Chip, 1/16W, 1%	603	STD	STD
2	R5 R15	1K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R2	221	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R4	200	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R3	3.40K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R12	43.2K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R17	453K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R14	49.9	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R9	68.1K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R7	84.5K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R11	0.01	Resistor, Chip, 1W, 1%	2512	STD	STD
4	J1-4	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
2	U2-3	TLV62065TDSG	IC, 3-MHz 2-A Step-Down Converter	SON	TLV62065TDSG	TI
7	TP1-2 TP4-6 TP8 TP12	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
6	TP3 TP7 TP9-11 TP13	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	Q1	BSC067N06LS3G	MOSFET, Nch, 60V, 50A, 6.7 milliohm	TDSON-8	BSC067N06LS3G	Infineon

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